

PNZ322D (PN322D)

Dual Division Silicon PIN Photodiode

For optical information systems

■ Features

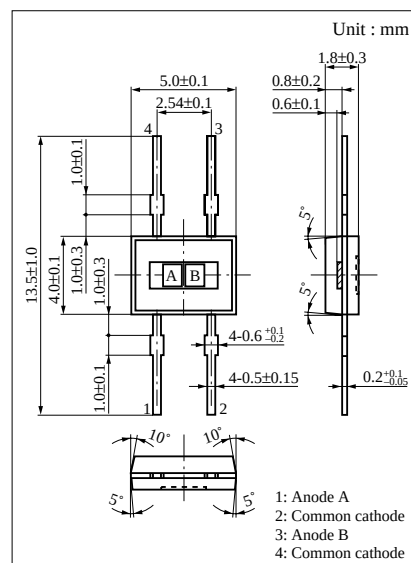
- Fast response : $t_r, t_f = 10 \text{ ns (typ.)}$
- Good photo current linearity
- Low dark current : $I_D = 10 \text{ nA (max.)}$
- Small plastic package and visible light cutoff resin (flat type)

■ Applications

- Auto focus sensor for still cameras and video cameras etc.
- Distance measuring systems
- Position sensor for automatic assembly lines
- Eye sensor for industrial robots

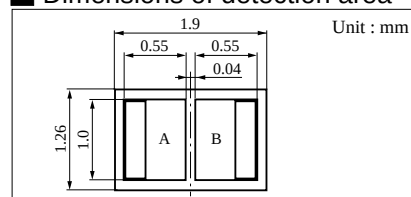
■ Absolute Maximum Ratings (Ta = 25°C)

Parameter	Symbol	Ratings	Unit
Reverse voltage (DC)	V_R	30	V
Power dissipation	P_D	30	mW
Operating ambient temperature	T_{opr}	-25 to +85	°C
Storage temperature	T_{stg}	-30 to +100	°C



Note) The PNZ0322 package consists of a visible light cutoff resin. Therefore the chips (A and B) shown in the drawing cannot actually be seen.

■ Dimensions of detection area



■ Electro-Optical Characteristics (Ta = 25°C)

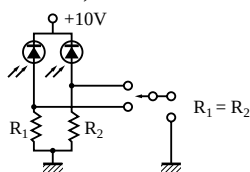
Parameter	Symbol	Conditions	min	typ	max	Unit
Reverse voltage (DC)	V_R	$I_R = 10\mu A$	30			V
Dark current	I_D	$V_R = 10V$			10	nA
Photo current	I_L^{*3}	$V_R = 10V, L = 1000 \text{ lx}^{*1}$	3	5		μA
Peak sensitivity wavelength	λ_p	$V_R = 10V$		940		nm
Response time	t_r, t_f^{*2}	$V_R = 10V, R_L = 1k\Omega$		10		ns
Capacitance between pins	C_t	$V_R = 10V, f = 1MHz$		3		pF
Acceptance half angle	θ	Measured from the optical axis to the half power point		65		deg.

Note) The indicated values for absolute maximum ratings and electro-optical characteristics are the values corresponding to individual elements.

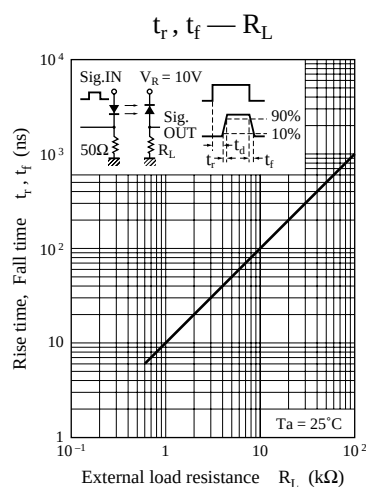
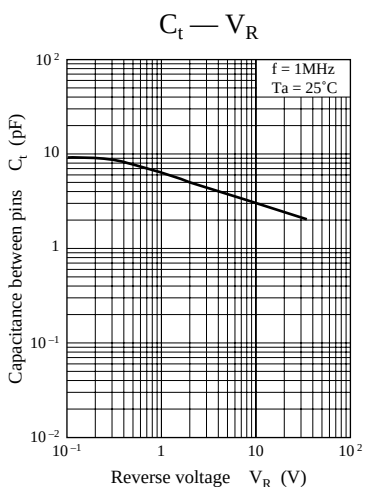
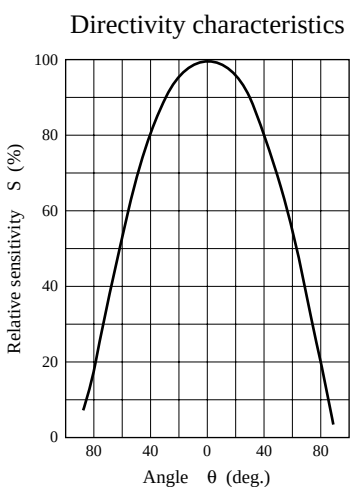
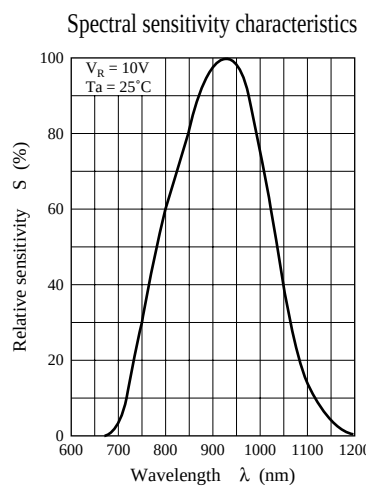
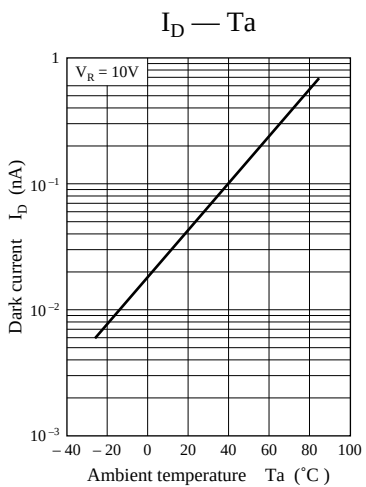
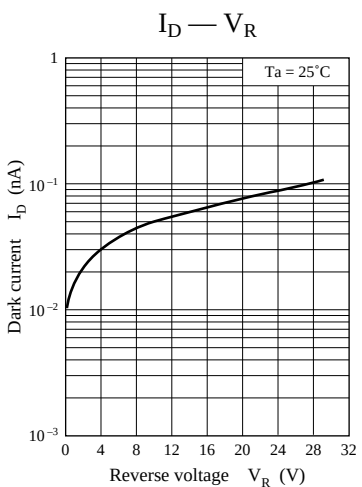
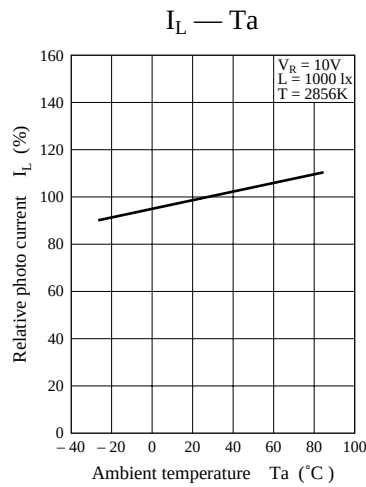
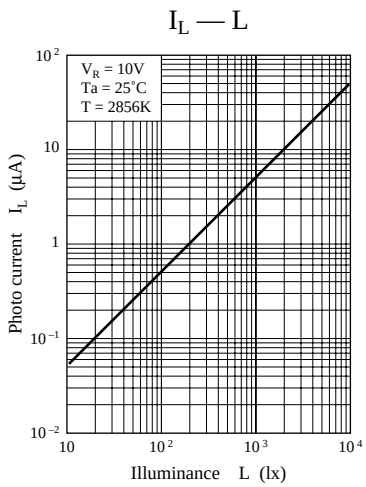
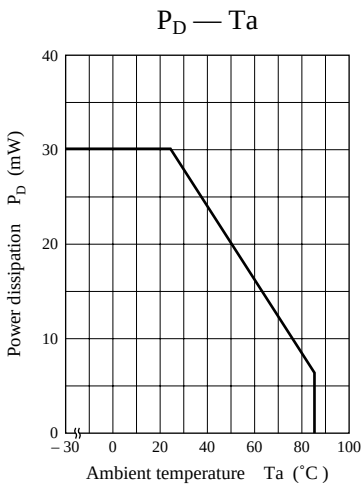
*1 White tungsten lamp light source (color temperature $T = 2856\text{K}$)

*² Semiconductor laser light source ($\lambda = 800\text{nm}$)

*3 Photo current measurement circuit



Note) The part number in the parenthesis shows conventional part number.



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